ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

IPC-1710A

OEM Standard for Printed Board Manufacturers' Qualification Profile

Developed by the OEM council of the IPC, the MQP sets the standard for assessing PWB manufacturers' capabilities and allows PWB manufacturers to more easily satisfy customer requirements.

IPC-1710A
May 2004

A standard developed by IPC

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The material in this standard was developed by the OEM Council of the Institute for Interconnecting and Packaging Electronic Circuits.

FOREWORD

It is not intended that this Manufacturers' Qualification Profile (MQP) satisfies all the requirements of the customer, however, conscientious maintenance of this document and or registration to ISO 9000 requirements should satisfy the major concerns. Thus, audits should be simpler, required less frequently, and facilitate less paper work as customers and suppliers work closer to meeting each others needs.

ACKNOWLEDGMENTS

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Although the IPC is grateful for all the involvement and individual contributions made in completing the MQP a special acknowledgment is extended to the following individuals. It was their dedication and foresight that made this publication possible.

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CONTENTS

SECTION 1.1
COMPANY DESCRIPTION

DATE COMPLETED
01 / March / 2014

GENERAL INFORMATION		
LEGAL NAME Sonic Technology (India), Inc.		
PHYSICAL ADDRESS C-9, GIDC Electronics Estate, Sector 25		
CITY Gandhinagar	STATE Gujarat	ZIP 382025
PROVINCE	COUNTRY India	
TELEPHONE NUMBER +91 79232 87517	FAX NUMBER +91 79232 87515	TELEX NUMBER
E-MAIL ADDRESS cad@sonictechindia.com	MODEM NUMBER	DATE FOUNDED 2002 ☐ PUBLIC ☒ PRIVATE
INTERNET URL www.sonictechindia.com	FTP SITE ftp.sonictechindia.com	

MANAGEMENT
PRESIDENT Mr. Robert M. Keisler
CHIEF EXECUTIVE OFFICER Mr. Roger Patel
VICE PRESIDENT OF MANUFACTURING Mr. Robert M. Keisler
VICE PRESIDENT OF MARKETING/SALES Mr. James Thompson
DIRECTOR OF QUALITY/CUSTOMER SERVICE Mr. Carl L Schlemmer
SENIOR MANAGER QUALITY Mr. J.V.Nagabhushan
WASTE TREATMENT MANAGER (POLLUTION PREVENTION) Mr. Himanshu Patel

CORPORATE DESCRIPTION		NUMBER OF EMPLOYEES CORPORATE	SITE	COMMENTS
DESIGN AND DEVELOPMENT		N/A	N/A	No design activities are being done at Sonic facility.
ENGINEERING		4	14	
MANUFACTURING CONTROL		1	5	
MANUFACTURING	DIRECT		88	
	INDIRECT		13	
QUALITY CONTROL	QUALITY ENGINEERS	1	9	
	INTERNAL AUDITORS		5	Internal auditors are part of management team from production & quality responsibilities.
GENERAL MANAGEMENT		5	3	
ADMINISTRATION		2	1	
TOTAL		13	138	We have one more PCB shop in USA: National Technology, Inc., 1101 Carnegie Street, Rolling Meadows, IL-60008, Near Chicago. Hence, in this document we have considered only those positions for number of employees under corporate heading, which are mainly supporting STII activities and are stationed at National Technology.

SECTION 1.2
SITE DESCRIPTION

(TO BE COMPLETED FOR EACH SITE)

DATE COMPLETED: 01 / March / 2014
ATTACH APPROPRIATE CHARTS (OPTIONAL)

MANUFACTURING FACILITY		
COMPANY NAME: Sonic Technology (India), Inc.		
PHYSICAL ADDRESS: C-9, GIDC, Electronics Estate, Sector 25		
CITY: Gandhinagar	STATE: Gujarat	ZIP: 382025
PROVINCE: -	COUNTRY: India	
TELEPHONE NUMBER: +91 79232 87517	FAX NUMBER: +91 79232 87515	TELEX:
E-MAIL ADDRESS: cad@sonictechindia.com	MODEM NUMBER: -	YEARS IN BUSINESS: 11
INTERNET URL: www.sonictechindia.com	FTP: ftp.sonictechindia.com	
PRINCIPLE RODUCTS/SERVICES/SPECIALTIES: Double Sided and Multilayer Printed Circuit Boards	BUSINESS CHARACTERIZATION (HIGH VOLUME, QUICK TURN-AROUND, ETC.): Medium to High volume Production	

FACILITY MANAGEMENT	TITLE	REPORTS TO (Function/Job Title)
OVERALL OPERATION RESPONSIBILITY FOR THIS SITE Mr. Roger Patel	CEO	
MANUFACTURING Mr. Shankar B.Patil	Production Manager	CEO/President
TECHNICAL/ENGINEERING Mr. Pankaj Patel	CAD/Engineering Manager	CEO/President
MATERIALS/PRODUCTION CONTROL Mr. Shankar B.Patil	Production Control	CEO/President
PURCHASING Mr. Himanshu Patel	Purchasing Manager	CEO
QUALITY Mr. J.V. Nagabhushan	Senior Manager Quality	CEO
SALES REPRESENTATIVE Mr. Roger Patel	CEO	
WASTE MANAGEMENT Mr. Himanshu Patel	Waste Treatment Manager	CEO

BUILDINGS				SYSTEMS (INDICATE % COVERAGE)						
	AGE	AREA (Sq. Ft.)	Construction (Wood/Brick)	Power Conditioning	Heating	Ventilation	Air Conditioning	Sprinklers (Fire Extinguishers)	Waste Treatment	Other
Office	11 years	9K	Brick	100%	NA	100%	100%	100%	NA	
Manufacturing	11 years	52K	Brick	100%	NA	100%	60%	100%	100%	
Storage	11 years	15K	Brick	100%	NA	100%	20%	100%	NA	
Planned additions	Work In-progress	30K	Brick							

SAFETY AND REGULATORY AGENCY REQUIREMENTS				
Are fire extinguishers functional and accessible to employees?	☒ YES	☐ NO	What is the distance to the nearest fire station? (in minutes)	5 Miles / 10 Minutes
Do you conform to local/federal environment protection agency requirements?	☒ YES	☐ NO	Date of last OSHA visit Date of last EPA (GPCB) visit	12 January 2014
Are you currently operating under a waiver or in violation of local government requirements?	☐ YES	☒ NO	Other Agency Audits, UL, ISO 9000, NECQ, CSA Approval and Number	☒ UL # E97071 ☒ ISO 9001:2008 ☐ CSA # _____ ☐ Other _____
Do you have a safety program? Describe below.	☒ YES	☐ NO	Hazardous Waste Number Trade Waste Account Number	NEPL-TSDF, 2030 Date:-29/03/2004

PLANT PERSONNEL (TOTAL EMPLOYEES)										
Regular	Contract	Office	Technical / Engineering	Production (direct & indirect)	Full-Time QA	Part-Time QA	Union	Non-Union	Union Name	Contract Expires (Date)
38	100	4	14	106	14	0	0	All (138)	N/A	N/A

COMMENTS

SECTION 2.1
PROCESS

DATE COMPLETED
01 / March / 2014

This section is intended to provide overview information on the processes used to fabricate printed board products.

Site Capability Snapshot (Please Check all that apply)

	Designators		Remarks
A	Conductor Forming Processes	☒Subtractive ☐Thin Foil Subtractive less than .5 oz. ☐Semi-Additive ☒Additive (Electro-less) ☒Black Hole ☐Thick Film Paste and Fire ☐Thin Film Semi-conductor Sputtering ☐Other:	Using copper clad laminates (print-etch) Electroless plating is exclusively for PTH Black hole process is exclusively for PTH
B	PTH Materials and Processes	☒Acid Copper ☐Pyro-Phosphate Copper ☐Full Built Electro-Less ☐Gold Paste ☐Copper Paste ☐Gold Conductor Sputtering ☐Nickel Conductor Sputtering ☐Other:	Copper electro-plating process
C	Permanent Over-plating	☒Tin ☐Tin-Lead ☐Tin-Nickel Alloy ☐Nickel ☐Nickel Gold (Hard) ☐Nickel Gold (Soft) ☐Nickel Rhodium ☐Conductive Polymer ☐Other:	Electroplating process

D	Permanent Selective Plating	☐Tin ☐Tin-Lead ☐Tin-Nickel Alloy ☐Nickel ☒Nickel Gold (Hard) ☒Nickel Gold (Soft) ☐Nickel Rhodium ☒Other: Immersion Silver	For TAB plating Electroless Nickel Immersion Gold
E	Permanent Mask or Coating	☐Photo Dry Film ☒Photo Liquid ☐Image Transfer Screen Mask ☐Conformal Coating Solder Mask ☐Cover Coat ☐Other:	LPISM process
F	Other Surface Finishes	☐Tin-Lead Fused ☐Immersion Tin ☒Solder Leveled ☐Roll Soldered ☐Electro-less Solder Fused ☐Solder Bumped Lands ☐Solder Paste Fused ☐Azole Organic Protective Covering ☐Flux Protective Covering ☒Other: Immersion Silver & ENiG Finishes	Both standard and lead-free HAL

SECTION 2.2
ELECTRICAL TEST EQUIPMENT

DATE COMPLETED
01 / March / 2014

This section is intended to provide overview information on the test equipment and testing capability of the manufacturer.

Site Capability Snapshot (Please Check the column that applies furthest to the right.)

	Designators		Remarks
A	Number of Nets	☐<200 ☐200 ☐500 ☐1000 ☐2000 ☐3000 ☐4000 ☐5000 ☒>5000 ☐Other:	
B	Number of Nodes	☐<500 ☐500 ☐1000 ☐2000 ☐3000 ☐4000 ☐5000 ☐6000 ☒>6000 ☐Other:	
C	Probe Point Pitch	☐>1.0 [.040] ☐1.0 [.040] ☐0.8 [.032] ☐0.65 [.025] ☐0.50 [.020] ☒0.40 [.016] ☐0.30 [.012] ☐0.20 [.008] ☐<0.20 [.008] ☐Other:	

D	Test % Single Pass	☐None ☐<60% ☐60% ☐70% ☐80% ☐90% ☒95% ☐99% ☒100% ☐Other:	Actual FPY is at 93% (Year 2013) 100% test of total production-run
E	Probe Accuracy (DTP)	☐>0.2 [.008] ☐0.2 [.008] ☐0.15 [.006] ☐0.125 [.005] ☐0.1 [.004] ☒0.075 [.003] ☐<0.075 [.003] ☐Other:	
F	Grid Density	☐Single Side Grid ☐Double Sided Grid ☒Double Density Grid ☒Double Density Double Sided ☐Quad Density ☐Double Sided Quad Density ☒Flying Probe ☐Other:	
G	Netlist Capability	☐Golden Board ☐IPC-D-356 ☒Net List Extraction ☒CAD/CAM Net List Compare ☐Other:	

H	Test Voltage	☐<20 VDC ☐20 VDC ☐40 VDC ☐60 VDC ☐80 VDC ☐100 VDC ☐500 VDC ☐1000 VDC ☐>1000 VDC ☒ Other: 12 VDC to 250 VDC	Range: 12 VDC to 250 VDC
J	Impedance Meas	☐Micro Section ☐Inboard Circuit ☐Coupon ☐Manual TDR ☐Automated TDR ☐Other:	Controlled impedance boards are currently not being produced at our facility.
K	Impedance Tolerance	☐None ☐>20% ☐20% ☐15% ☐10% ☐7% ☐5% ☐2% ☐<2% ☐Other:	Not applicable

SECTION 2.3
PRODUCT TYPE

DATE COMPLETED
01 / March / 2014

This section is intended to provide overview information on the printed board product types being fabricated by the manufacturer.

Site Capability Snapshot (Please Check all that apply.)

Designators			Remarks
A	Product Type	☒Rigid Printed Board	
		☐Flex Printed Board	
		☐Rigid/Flex Board	
		☐Rigid Back Plane	
		☐Molded Product	
		☐Ceramic Printed Board	
		☐Multichip Module	
		☐Liminated Multichip Module	
		☐Deposited Dielectric Multichip Modules	
		☐Other:	
B	Circuit Mounting Type	☒Single Sided	
		☒Double Sided	
		☒Multilayer	
		☐Single-sided Bonded to Substrate	
		☐Double-sided Bonded to Substrate	
		☐Multilayer Bonded to Substrate	
		☐Constrained Multilayer	
		☐Distributed Plane Multilayer	
		☐Other:	
C	Via Technology	☐No-Vias	
		☒Thru Hole Vias	
		☒Buried Vias	Trial production in-progress
		☒Blind Vias	Trial production in-progress
		☒Thru Hole & Blind Vias	Trial production in-progress
		☒Thru Hole & Buried Vias	Trial production in-progress
		☐Thru Hole Buried & Blind Vias	
		☐Buried & Blind Vias	
		☒Other: Plugged Vias	Plugging using non-conductive polymer ink

D	Laminate Material	☐Phenolic ☐Epoxy Paper ☒Epoxy Glass ☐Modified Epoxy Composite ☐Polyamide Film & Reinforce ☐Cyanate Ester ☐Teflon ☐Ceramic Glass Types ☐Various Combinations ☒Other: RoHS Compliant Laminates	
E	Core Material	☒No Core ☐Polymer ☒Copper ☐Aluminum ☐Graphite ☐Copper Invar/Copper ☐Copper Moly/Copper ☐Other:	Prepreg or un-claded inner cores / laminates Copper claded inner cores and laminates. Copper foil for top & bottom layers of MLBs
F	Copper Thickness (Oz.)	☐1/8 Minimum ☐1/4 Minimum ☐3/8 Minimum ☒1/2 Nominal ☒1 Nominal ☒2 Nominal ☒3-5 Max ☐6-9 Max ☐>10 ☐Other:	
G	Construction	☒≤4 Planes ☒>4 Planes ☒THK to TOL ≤0.2 mm ☐THK to TOL >0.2 mm ☒Bow/Twist ≤1% ☐Bow/Twist >1% ☒≤0.3 mm Profile Tolerance ☐0.3 mm Profile Tolerance ☐Other:	

H	Coatings and Markings	☒≤0.1 mm Mask Clearance ☒>0.1 mm Mask Clearance ☒One Side (Legend) ☒Two Side (Legend) ☒None (Legend) ☒UL Material Logo ☒U.L. V_0 Logo ☐U.L. V_1 Logo ☐U.L. V_2 Logo ☐ Other:	

SECTION 2.4
PRODUCT COMPLEXITY

DATE COMPLETED
01 / March / 2014

This section is intended to provide overview information on product complexity being fabricated by the manufacturer.

(Please check the column that applies farthest to the right)

Designators			Remarks
A	Board Size Diagonal	☐<250 [10.00] ☐250 [10.00] ☐350 [14.00] ☐450[17.50] ☒550 [21.50] ☐650 [25.50] ☐750 [29.50] ☐850 [33.50] ☐>850 [33.50] ☐Other:	
B	Total Board Thickness	☐1,0 [.040] ☐1,0 [.040] ☐1,6 [.060] ☐2,0 [.080] ☐2,5 [.100] ☒3,5 [.135] ☐5,0 [.200] ☐6,5 [.250] ☐>6,5 [.250] ☐Other:	
C	Number Conductive Layers	☒1-4 ☒5-6 ☒7-8 ☐9-12 ☐13-16 ☐17-20 ☐21-24 ☐25-28 ☐>28 ☐Other:	Produced in volume run Produced in volume run Produced in small quantities

D	Dia Drilled Holes	☐>0,5 [.020] ☐0,5 [.020] ☐0,4 [.016] ☐0,35 [.014] ☐0,30 [.012] ☒0,25 [.010] ☐0,20 [.008] ☐0,15 [.006] ☐<0,15 [.006] ☐Other:	
E	Total PTH TOL (Max-Min)	☐>0,250 [.010] ☐0,250 [.010] ☐0,200 [.008] ☐0,150 [.006] ☐0,125 [.005] ☐0,100 [.004] ☒0,075 [.003] ☐0,050 [.002] ☐<0,050 [.002] ☐Other:	
F	Hole Location TOL DTP	☐>0,50 [.020] ☐0,50 [.020] ☐0,40 [.016] ☐0,30 [.012] ☐0,25 [.010] ☐0,20 [.008] ☐0,15 [.006] ☒0,10 [.004] ☐<0,10 [.004] ☐Other:	
G	Internal Layer Clearance (Min)	☐>0,350 [.014] ☐0,350 [.014] ☐0,250 [.010] ☐0,200 [.008] ☐0,150 [.006] ☒0,125 [.005] ☐0,100 [.004] ☐0,075 [.003] ☐<0,075 [.003] ☐Other:	Assumed as spacing between tracks

H	Internal Layer Conductor Width (Min)	☐>0,250 [.010] ☐0,250 [.010] ☐0,200 [.008] ☐0,150 [.006] ☒0,125 [.005] ☐0,100 [.004] ☐0,075 [.003] ☐0,050 [.002] ☐<0,050 [.002] ☐Other:	
J	Internal Layer Process Allowance	☐>0,100 [.004] ☒0,100 [.004] ☐0,075 [.003] ☐0,050 [.002] ☐0,040 [.0015] ☐0,030 [.0012] ☐0,025 [.001] ☐0,020 [.0008] ☐<0,020 [.0008] ☐Other:	Assumed as scaling factor
K	External Layer Clearance (Min)	☐>0,350 [.014] ☐0,350 [.014] ☐0,250 [.010] ☐0,200 [.008] ☐0,150 [.006] ☒0,125 [.005] ☐0,100 [.004] ☐0,075 [.003] ☐<0,075 [.003] ☐Other:	Assumed as spacing between tracks
L	External Layer Conductor Width (Min)	☐>0,250 [.010] ☐0,250 [.010] ☐0,200 [.008] ☐0,150 [.006] ☒0,125 [.005] ☐0,100 [.004] ☐0,075 [.003] ☐0,050 [.002] ☐<0,050 [.002] ☐Other:	

M	External Layer Process Allowance	☐>0,100 [.004] ☒0,100 [.004] ☐0,075 [.003] ☐0,050 [.002] ☐0,040 [.0015] ☐0,030 [.0012] ☐0,025 [.001] ☐0,020 [[.0008] ☐<0,020 [.0008] ☐Other:	Assumed as scaling factor
N	Feature Location DTP	☐>0,50 [.020] ☐0,50 [.020] ☐0,40 [.016] ☐0,30 [.012] ☐0,25 [.010] ☐0,20 [.008] ☐0,15 [.006] ☒0,10 [.004] ☐<0,10 [.004] ☐Other:	

All Dimensions are in millimeters [inches shown in brackets]

SECTION 2.5
QUALITY DEVELOPMENT

DATE COMPLETED
01 / March / 2014

This section is intended to provide overview information on the quality systems in place in the manufacturing facility.

Site Capability Snapshot (Please Check all that apply.)

Designators			Remarks
A	Strategic Plan	☒Functional Steering Committee Formed ☒TQM Plan & Philosophy Established & Published ☒Documented Quality Progress Review ☒Implementation & review of Project Team Recommendations ☒TQM Communicated throughout organization ☒Controlled New process Start-up ☒Management Participates in TQM Audits ☒Employee Recognition Program ☒Total TQM Plan/Involvement Customer Training ☒Other: ISO Certified (By: AQA under ANAB Accreditatiion)	
B	Employee Involvement	☒Certified Training Available ☒Training of Employee Base ☒TQM Team Trained ☒Design of Experiment Training and Use ☒New Process Implementation Training ☒Support Personnel Training ☐Advanced Statistical Training ☒Quality Functional Deployment ☒Ongoing Improvement Program for Employees ☐Other:	
C	Quality Manual	☐Quality Manual Started ☒Generic Quality Manual for Facility ☐10% of manufacturing depts. have process specifications ☐25% of manufacturing depts. have process specifications ☐50% of manufacturing depts. have process specifications ☐Non-manufacturing Manuals Developed ☐25% of all departments have quality manuals ☐50% of all departments have quality manuals ☒All Manufacturing and support depts. have controlled quality manual ☐Other:	

D	Instructions	☐Work Instructions Started ☐Quality Instructions Started ☐10% Work Instructions Completed ☐10% Quality Instructions Completed ☐25% Work Instructions Competed, Controlled ☐25% Quality Instructions Completed, Controlled ☐50% Work Instructions Completed, Controlled ☐50% Quality Instructions Completed, Controlled ☒Quality and work Instructions Completed, Controlled ☐Other:	
E	SPC Implementation IPC-PC-90	☐Plan Exists ☐Training Started ☒Process Data Collected & Analyzed ☐All Employees Trained ☐First Process Stable & Capable ☒Several Major Processes Stable & Capable ☒Continued Improvement of Stable Processes ☐Additional Mfg. Processes under Control ☐All Processes Under Control ☐Other:	
F	Supplier Programs/Controls	☒Supplier Rating Program ☐Monthly Analysis Program ☒Key Problems Identified ☐Supplier Reviews Performance Data provided ☐TQM Acceptance by suppliers ☐10% of Suppliers Using SPC ☐25% of Suppliers Using SPC ☐50% of Suppliers Using SPC ☒All Key Suppliers using certified parts program ☐Other:	
G	Third Party IPC-QS-95	☐Instrument Controls in Place ☐Measurement System in Control IPC-PC-90 ☒Document Controls in Place ☒Reduced Lot Sampling ☐10% of Processes Under Audit Control ☒50% or Greater of Processes Under Audit Control ☐ISO-9003 Certified ☐ISO-9002 Certified ☒ISO-9001:2008 ☐Other:	Sampling checks at AQL stage

SECTION 3

DATE COMPLETED
01 / March / 2014

EQUIPMENT PROFILE (Pre-Site Audit)

* Examples of equipment limitations include: min/max board size & min/max working area

3.1 PHOTOTOOL CAPABILITY	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) AOI of photo tool	☒	☐	Camtek ORION	2	For selective/critical types only
B) AOI CAD reference (CAM)	☒	☐	Using CAM-350 Station	1	Additionally, we have 14 Barco "U CAM" Stations. 11 at STII & 3 at NTI.
C) Photo plotting	☒	☐	Gerber "Silver Writer" Laser Plotter	1	
D) Photo reductions	☒	☐	Gerber "Silver Writer" Laser Plotter	1	For phototool scaling purpose
E) Film scan and conversion	☒	☐	Diazo Exposure Machines Technilith Dry Developer	2 1	For image duplication from black and white (silver halide) films to diazo films.
F) Film processing ☐ air-dried ☐ force-dried ☒ processed in automatic processor	☒	☐	Film Processors: (a) DuPont (b) Glunz & Jensen	 1 1	
G) Media types ☒ silver halide film ☒ glass ☒ diazo	☒	☐	Glass-Glass Registration System from Multiline (for inner cores of MLBs)		Master Films: Silver Halide B&W Production Copies: Diazo Films

3.2 DRILLING EQUIPMENT	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Manual	☐	☒			
B) Optical (single spindle)	☐	☒			
C) N.C. Drill	☒	☐	Excellon Mark VI Pluritec GIGA 8888	4 3	

3.3 ROUTING EQUIPMENT	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Edge beveller	☒	☐	Excellon Mark V	1	We procure cut panels in ready to use with edge beveled for standard format sizes. We use "Excellon machine" for routing in case of multilayer panels.
B) Hand router (pin router)	☐	☒			
C) N.C. router	☒	☐	Excellon Mark VI	1	
D) N.C. driller/router	☒	☐	Excellon Mark V	3	
E) Scoring (profile)	☐	☒			Profile scoring concept is not clear
F) Scoring (straight Line)	☒	☐	Gecko and Accuscore Machines	3	Straightline & jump score

3.4 MECHANICAL EQUIPMENT	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Punch press	☐	☒			
B) Shear	☒	☐	Wysong Cutter Machine	1 1	For laminate shearing For prepreg cutting
C) Milling machine	☐	☒			

3.5 HOLE PREPARATION (DESMEAR)	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Permanganate	☒	☐	Hand Line	1	
B) Plasma	☐	☒			
C) Mechanical	☐	☒			
D) Etchback	☒	☐	Hand Line	1	

3.6 PRIMARY IMAGE APPLICATION	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Dry film	☒	☐	Dynachem Laminators Model: 300	2	
B) Hand screening	☐	☒			
C) Machine screening	☐	☒			
D) Wet film	☐	☒			
E) Liquid photoimageable	☐	☒			

3.7 TYPE OF TREATMENT FOR MULTILAYER INNERLAYERS	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Brown oxide	☒	☐	Atotech Horizontal Process	1	
B) Red oxide	☐	☒			
C) Copper scrub	☐	☒			
D) Durabond	☐	☒			
E) Other	☐	☒			

3.8 LAMINATION	YES	NO	MATERIAL	QTY	APPLICATION TECHNIQUE
A) High pressure	☒	☐	TMP Vacuum Press	2	
B) High temperature	☒	☐			
C) Vacuum	☒	☐			
D) Vacuum assist	☒	☐			
E) Foil heat assist	☒	☐			
F) Separate cool-down	☒	☐			

3.9 ELECTROLESS COPPER PLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Fully additive application	☒	☐	Hand Line	1	
B) Electroless deposition (semi additive)	☐	☒			
C) Through-hole and via	☒	☐			

3.10 COPPER ELECTROPLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Copper sulfate	☒	☐	Hand Line	1	8 Manual Copper, 2 Manual Tin Stations and Treatment Tanks
B) Pyrophosphate	☐	☒			
C) Copper fluoborate	☐	☒			
D) Other	☐	☒			

3.11 TIN/LEAD SURFACE PLATINGS/COATINGS	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Tin/lead electroplated	☐	☒			
B) Immersion tin or tin/lead (electroless)	☐	☒			
C) Hot air solder leveled (HASL)	☒	☐	Penta Solder Leveling System	2	Standard & Lead-free processes

3.12 FUSING PROCESSES	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) I.R. reflow	☐	☒			
B) Hot oil reflow	☐	☒			
C) Horizontal (hot air level)	☐	☒			
D) Vertical (hot air level)	☒	☐	See 3.11 Above	2	Standard & Lead-free processes

3.13 NICKEL SURFACE PLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Electroless nickel	☒	☐	Hand Line	1	
B) Electroplated nickel	☒	☐	Hand Line	1	For TAB plating

3.14 GOLD SURFACE PLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Electroless gold	☒	☐	Hand Line	1	
B) Electroplated gold	☒	☐	Hand Line	1	For TAB plating

3.15 PALLADIUM SURFACE PLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Electroless palladium (immersion)	☐	☒			
B) Electroplated palladium	☐	☒			

3.16 SOLDERMASK	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Screened deposited image	☐	☒			
B) Dry film photoimageable	☐	☒			
C) Liquid photoimageable	☒	☐	Circuit Automation DP1500 & DP10	3	
D) Dry film/liquid combination	☐	☒			

3.17 ORGANIC SURFACE PROTECTION	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Benzotriazole	☐	☒			
B) Imidazole	☐	☒			
C) Benzimidazole	☐	☒			

3.18 MICROSECTION CAPABILITY	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Manual	☐	☒			
B) Single cavity automated	☒	☐	Buehler & Bainpol Metco	2	
C) Multiple cavity automated	☐	☒			
D) Plating thickness analysis	☒	☐	Nikon Microscope	1	

3.19 CHEMICAL ANALYSIS	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Etching chemistry	☒	☐	Equipped Chemical LAB	1	Alkaline Etchant
B) Plating chemistry	☒	☐	Equipped Chemical LAB with Perkin Elmer AAS Unit	1	Acid Copper, Tin, Nickel, Gold and Silver.
C) Effluent (PPM) analysis	☒	☐	Equipped Chemical LAB	1	

3.20 ELECTRICAL TEST EQUIPMENT	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Continuity and shorts	☒	☐	Bed of Nails (Mania Versa Tower) Flying Probe Testers	2 2	
B) Fixture development	☒	☐	NC Drill	1	
C) Flying probe test	☒	☐	ATG A3 Testers	2	Same as mentioned at 3.20 (A)
D) Impedance control	☐	☒			

DATE COMPLETED
01 / March / 2014

MASTER EQUIPMENT LISTING

FORM MQP 10 REF:

Please complete a Master Equipment List. You may use your own form or the MQP Form 10.

IDENTIFICATION	EQUIPMENT NAME/DESCRIPTION	MANUFACTURER TYPE/MODEL	EQUIPMENT LIMITS	ACCURACY	CALIBRATION FREQUENCY	REMARKS

Please refer to the attached documents for details on equipments & calibration status:

(a) Equipments PDF File ➔ 
Equipment Status_NOV 2013.pc

(b) Calibration PDF File ➔ 
Calibration Status_2013-14.pdf

DATE COMPLETED
01 / March / 2014

SECTION 4
TECHNOLOGY PROFILE SPECIFICS

4.1 ADMINISTRATION

4.1.1 CAPACITY PROFILE	EST %	COMMENTS
A) Total annual capacity in square meters (surface area)	120,000	Based on two sides of panels (surface area)
B) Presently running at ____ % of capacity	60%	Based on one main shift operation with second & night shifts in some of the departments.

4.1.2 PERCENTAGE OF DOLLAR VOLUME	EST %	COMMENTS
A) Single sided (rigid)	1.0	Data is based on 2013 production records
B) Double sided (rigid)	44	
C) Multilayer (rigid)	55	
D) Single side (unreinforced-flex)	0	
E) Double sided (unreinforced-flex)	0	
F) Multilayer (unreinforced-flex)	0	
G) Multilayer (rigid/flex) ——	0	

4.1.3 PANEL PRODUCTION PROFILE	UNITS PER MONTH
A) Size of a production lot in panels	
1) Normal	100 panels Note: Multiple “lots” are used for large releases
2) Smallest	1 panel
B) Number of panels per month	
1) High Production	22,200
2) Medium Production	17,000
3) Low Production	11,000
3) Short run	5200
4) Prototype	Prototype done at this facility as per customer requirements

C) Average lead time (delivery) as defined in B)	
1) High Production	4 weeks
2) Medium Production	3 weeks
3) Low Production	2 weeks
3) Short run	2 weeks
4) Prototype Quick turn - No. of days 10.	Lead-time is ten days
D) Product delivered in full panel or array sub-panel format	
1) Total in panel or array format	70%
2) Scored format	60%
3) Tab breakaway format	10%
4) Other	0%
5) Total to customer layout	85%
6) Total to manufacturing layout	15%
E) Product delivered in board format	
1) Total in board format	30%
2) Extracted: scored to size	1%
3) Extracted: sheared to size	0%
4) Extracted: routed to size	100%

4.1.4 APPROVAL AND CERTIFICATION	YES	NO	COMMENTS
A) Company approvals			
1) UL approval	☒	☐	Our products are approved by UL. UL File # E97071
2) Canadian standards	☐	☒	
3) MIL-P-55110	☐	☒	
4) MIL-P-50884	☐	☒	
5) ISO-9002	☐	☒	
6) ISO-9001:2008	☒	☐	 Certificate_2011-14.pdf Our existing certificate has a validity of only till 9th FEBRUARY 2014. Re-registration assessment is completed on 29th & 30th January 2014.

7) ISO-14000	☐	☒	
8) BABT	☐	☒	
9) EEC	☐	☒	
10) Customer Satisfaction	☒	☐	Tracked and compiled data on monthly basis as per internal format.
B) Other certification information			
1) Laminate	☒	☐	Standard brands like Isola & Nanya laminates are in use.
2) Quality standards	☒	☐	Our product conforms to customers specification, wherever available. Otherwise, we refer to IPC specifications: IPC 600 & IPC 6012.
3) Equipment calibration	☒	☐	Refer to detailed Master Equipment Listing on page number 22.

4.1.5 CUSTOMER INTERFACE PROFILE	**YES**	**NO**	**COMMENTS**
A) Modem capability	☒	☐	We receive customer data through FTP (File Transfer Protocol) and having 2.1 mbps in-house internet line modem (CYGNUS).
B) Baud rate	☒	☐	2.1 mbps
C) Data verification technique	☒	☐	Through CAD system using UCAM software
D) Engineering change order process	☒	☐	Through “Pro Cim” system
E) Job status reporting to customers	☒	☐	“Pro Cim” system generated data to customer by e-mail

4.1.6 OTHER CAPABILITIES	**YES**	**NO**	**COMMENTS**
A) Facility research and development	☐	☒	No R&D service offered by Sonic
B) (Automated) On-line shop floor control/MRP system	☒	☐	“Pro Cim” system customized for facility requirements and needs.
C) Process control system	☒	☐	“Pro Cim” system customized for facility requirements and needs.
D) Operator training system	☒	☐	Documented utilizing facility network system.

4.2 PROCESS ORIENTATION

4.2.1 LAMINATE MATERIAL	EST %	COMMENTS
A) Most commonly used laminates (G10, FR4, etc.)	45 10 45	Brand name: Nanya & Type: FR4 Brand name: Isola & Type: FR406 Brand name: Isola & Type: 185 HR & 370 HR
B) Other laminate material		
1) Planar resistor layers	0	UL approved ☐
2) BT epoxy	0	UL approved ☐
3) Kevlar	0	UL approved ☐
4) Teflon	0	UL approved ☐
5) Polyimide	0	UL approved ☐
6) Cyanate ester	0	UL approved ☐
7) Other	100	UL approved ☒ Ref: UL File #E97071 Various high Tg & Td RoHs compliant laminates, as per customer requirements.
C) Specification to which laminate is purchased (check all that apply) ☐MIL-P-13949 ☐IPC-4204 ☒IPC-4101 ☒UL Approved ☐IPC-4103 ☐Other ☐IPC-4202 ☐IPC-4203		
D) Laminate storage ☒ Uncontrolled ☒ Humidity controlled ☒ Temperature controlled ☐ Dry box ☐ JIT inventory		Rigid laminates are stored under ambient environment. Prepreg materials are stored under humidity and temperature controlled environment.
E) Panel size configurations in X, Y dimensions maximum X 457.2 mm; Y 609.6 mm minimum X 304.8 mm; Y 406.4 mm other X____ mm; Y____ mm		Standard Format Standard Format **Note:** Other panel sizes are reviewed to get best possible material utilization based on customer's board or array dimensions.

4.2.2 PROCESS PRECISION SPECIFICS	YES	NO	VALUE	COMMENTS
A) Maximum printed board thickness built in volume				
1) Single sided	X		.125”	
2) Double sided	X		.125”	
3) Multilayer	X		.130”	
4) Rigid flex		X	N/A	
B) Printed board electrical performance capability				
1) Impedance control	☐	☒		
2) Capacitance control	☐	☒		
3) Micro strip boards	☐	☒		
C) Tooling system description				
1) Same holes in panels used for all processes	☒	☐		
2) Optical registration	☒	☐		Process: Multiline system for multilayer film and post etch punch.
3) Other	☐	☐		

4.2.3 OTHER PROCESS ORIENTATION SPECIFICS	YES	NO	SYSTEM	COMMENTS
A) Solder mask over bare copper	☒	☐		
B) Plating/coating information				
1) Tin/lead reflow	☐	☒		
2) Hot air leveling	☒	☐		
3) Azole organic	☐	☒		
4) Conductive	☒	☐		Immersion Silver & ENiG finishes
C) Hole formation				
1) Hole cleaning	☒	☐		High-pressure wash
2) Hole cleanliness verified	☒	☐		Visual checks

4.3 PRODUCT DESCRIPTION

***CONSISTENCY IMPLIES YIELDS IN EXCESS OF 80%**

4.3.1. THROUGH HOLE INSERTION	EST %	SIZE (MM) - +/- TOL	COMMENTS
A) Smallest conductor width and tolerance produced with consistency			
1) Outer layers (print and etch)	5%	Size 0.127 mm Tol ± 0.05 mm	Based on one ounce copper
2) Inner layers (print and etch)	30%	Size 0.127 mm Tol ± 0.050 mm	Based on one ounce copper
3) Outer layers (plated)	30%	Size 0.127 mm Tol ± 0.050 mm	Based on one ounce copper
4) Inner layers (plated)	N/A	Size _____ mm Tol ± _____ mm	
5) Outer layers (additive plating)	N/A	Size _____ mm Tol ± _____ mm	
6) Inner layers (additive plating)	N/A	Size _____ mm Tol ± _____ mm	
B) Smallest plated-through hole (PTH) and tolerance consistently produced in 1.5 mm thickness material or multilayer board			
1) Minimum PTH diameter	15%	Size 0.254 mm Tol ± 0.076 mm	
2) Largest panel where this hole can be controlled (across diagonal)	15%	Size 762 mm Tol ± 0.0762 .mm	Size mentioined is based on panel diagonal dimension of 24” X 18” panel format.
C) Largest hole size that can be drilled and plated through in a 1.25 mm diameter land while maintaining an annular ring of 0.125 mm in large/small boards			
1) Largest board size (across diagonal)		Size 762 mm	Hole size: Drilled size and not finished.
2) Largest hole diameter		Size 0.9144 mm	
3) Smallest board size (across diagonal)		Size 25.4 mm	Boards are processed in array / bigger panel formats as per production requirement
4) Largest hole diameter		Size 0.9144 mm	
D) Surface mount land pattern pitch (check all that apply) ☒1.27mm [.050] ☒0.63mm [.025] ☒0.5mm [.020] ☐0.4mm [.016] ☐0.3mm [.012] ☐0.25mm [.010] ☐Other _____ .			0.5 mm (.020”) pitch is our minimum process capability.
E) Solder mask dam between lands (check all that apply) ☒1.27mm [.050] ☒0.63mm [.025] ☒0.5mm [.020] ☒0.4mm [.016] ☒0.3mm [.012] ☒0.25mm [.010] ☒Other .004”			Minimum DAM of 0.1016 mm (.004”) is our process capability.
F) Flatness tolerance (bow & twist) after reflow or solder coating ☐1.5% ☒1.0% ☐0.5% ☒Other 0.75%			As per IPC 600 & 6012 specifications.

4.3.2 PRODUCT QUALITATIVE AND QUANTITATIVE INFORMATION	YES	NO	QUANTITY OF PANELS	NUMBER or DIMENSION	COMMENTS
A) Multilayer layer count					
1) Maximum layers fabricated in volume (Maximum Lot)	X				6 layers in production mode. Maximum quantities vary depending on Sales booking.
2) Maximum layers fabricated in prototype (Minimum Lot)	X				8 layers in small run lot.
B) Buried vias produced consistently in volume	☐	☒			It is under trial-run.
1) Size					
2) Number of layers					
B) Blind vias produced consistently in volume	☐	☒			It is under trial-run.
1) Size					
2) Number of layers					
1) Controlled depth drilling	☐	☒			Done for counter-sink holes both PTH & NPTH.
2) Total number of layers					

4.4. TESTING CAPABILITY

4.4.1 TEST AND TEST EQUIPMENT CAPABILITY	YES	NO	COMMENTS
A) SMT centerline pitch that can be electrically tested ☒ 0.63mm [.025] ☒0.5mm [.020] ☐ 0.4mm [.016] ☐ 0.3mm [.012] ☐ 0.25mm [.010] ☐ Other			Our testing process capability is 0.5 mm (.020") minimum pitch.
B) Double sided simultaneous electrical testing	☒	☐	Using Flying Probe / Bed of Nails Testers.
1) Equipment type	☒	☐	Flying Probe Tester (ATG A3) & Bed of Nails Tester (Mania "Versa Tower")
2) X-ray fluorescence inspection equipment	☒	☐	Gnenbrook X-Ray Inspection Unit. CMI Unit - Model# XRX 990-D
3) TDR equipment	☐	☒	
4) Hi-pot test equipment	☐	☒	
5) Four-wire kelvin tester	☐	☒	
6) Capacitance meter	☐	☒	
7) Cleanliness testing	☐	☒	

4.4.2 AUTOMATED OPTICAL INSPECTION USAGE	EST %	COMMENTS
A) Before etching	0	
B) After etching	40	
C) Internal layers	80	
D) Final inspection	0	
E) Other	0	
F) Conductor/clearance normally inspected by AOI equipment		
1) ☐ 0.05mm [.002]		
2) ☐ 0.05-.10mm [.002-.004]		
3) ☒ >.10mm [.004]		AOI use is primarily for inner cores of multilayer boards and dense double sided boards. Photo tool AOI inspection as per manufacturing feasibility.
4) ☒ Planes		We do sampling AOI.
G) CAD download to AOI	100%	

DATE COMPLETED
01 / March / 2014

SECTION 5
QUALITY PROFILE

GENERAL INFORMATION	
COMPANY NAME Sonic Technology (India), Inc.	
CONTACT Mr. J.V. Nagabhushan	
TELEPHONE NUMBER +91-79-23287517	FAX NUMBER +91-79-23287515

This section of the Manufacturer's Qualification Profile is intended to describe the Total Quality Management (TQM) activity in place of being implemented at the manufacturing facility identified in the site description of this MQP.

To ease in the task of identifying the TQM program being planned or underway at the manufacturing site, the activities have been divided into twenty sections which when completed, provide the total picture of the posture toward managing quality issues. Each section contains a number of questions with regard to the topic under review.

It is not the intent to have the questions be all encompassing, nor is every question applicable to all manufacturers. However, identification of the status, related to each questions, when considered as a whole will convey an impression of the progress that the company has achieved in adopting the principles of total quality management.

The twenty sections, in order of the occurrence are:

5.1 General Quality Programs
5.2 New Products/Technical Services
5.3 Customer Satisfaction
5.4 Computer Integrated Manufacturing
5.5 Process Documentation
5.6 Quality Records
5.7 Skill, Training & Certification
5.8 Subcontractor Control
5.9 Calibration Control
5.10 Internal Audits
5.11 Statistical Process Control
5.12 Problem Solving
5.13 In-Process Control
5.14 Receiving Inspection
5.15 Material Handling
5.16 Non-Conforming Material Control
5.17 Inspection and Test Plan
5.18 Product Inspection/Final Audit
5.19 Tooling Inspection, Handling, & Storage
5.20 Corrective Action

Each section provides a status report related to each question. The question may not be applicable, no activity has started as yet, or the company may have developed an approach to the issues raised by the questions. An (X) is indicated in the appropriate column. If deployment/implementation has started, the status is reported as percent deployment; this is indicated in column 4. The percentage number closely approximates the status of deployment. If deployment exists, the percentage results that have been achieved is indicated in column 5. Results are based on expected goals. Not providing percent information in either the deployment or results column implies a lack of activity in the particular area.

The quality descriptions requested are completed on the following pages by checking (X) the appropriate column to reflect the status of the manufacturing facility TQM program. Additional information may be provided as comments shown below, or on individual sections, or additional sheets as necessary.

COMMENTS
Sonic Technology (India), Inc. is an ISO 9001-2008 certified company. Our certification body is AQA, having ANAB accreditation.
AQA is now merged with NSF-ISR, USA. A copy of ISO certificate is attached, please refer to Section 4.1.4 (6) of this document.

5.1 GENERAL QUALITY PROGRAMS		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are quality objectives and responsibilities clearly stated, widely distributed and understood through the company?			X	100	90
2.	Is there a quality function or well defined organization which provides customer advocate guidance to the total organization and is this position fully supported by management?			X	100	100
3.	Does a quality measurement system exist with clearly defined metrics and is it utilized as a management tool?			X	100	100
4.	Are work instructions approved and controlled; and are they under revision control?			X	100	100
5.	Are the quality procedures and policies current and available at the point of application; and are they under revision control?			X	100	100
6.	Are benchmark and customer satisfaction studies done to determine best in class for all products, services, and administrative functions; and are quality goals set?			X	85	85
7.	Are Statistical Process Control (SPC) principles understood by all levels of management?			X	100	80
8.	Are there programs with sufficient resources assigned to support corrective actions and prevention?			X	100	100
9.	Does management solicit and accept feedback from the work force?			X	100	100
10.	Is there management support of ongoing training (including quality training), and is it documented by an organizational training plan?			X	100	100
11.	Are there regular management reviews of elements of the quality improvement process, including feedback for corrective action, and are the results acted upon?			X	100	100
12.	Are the quality and reliability goals aggressive relative to customer expectations and targeted at continuous improvement?			X	100	100
13.	Are the people who are responsible for administering the quality assurance function technically informed?			X	100	100
14.	Does Management have a “defect prevention” attitude to achieve continuous improvement?			X	100	100

5.2 NEW PRODUCTS/TECHNICAL SERVICES		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Do new product/technology/service development policies and procedures exist, and do they result in clearly defined project plans with appropriate measureables and approvals?			X	70	70
2.	Is quantitative benchmarking used to evaluate all new products/technologies/services in comparison to best-in-class offerings?			X	70	70
3.	Does a roadmap exist to ensure continued development of leading edge, best-in-class products/technology/services?			X	80	80
4.	Is the capability of each operation which controls critical-to-function characteristics for new products, fully certified?			X	100	100
5.	Are statistical tools used in the development of robust (high yield) new processes, products, and services?			X	80	80
6.	When new product/technology/service requires a new process, is it developed jointly and concurrently with the customer and/or suppliers?			X	100	80
7.	Are design reviews conducted on a scheduled basis which properly address the process capability indices of critical-to-function and product/service characteristics?			X	100	80
8.	Is the new product/technology/service, as produced by the process, verified to meet all customer satisfaction requirements?			X	100	100

COMMENTS

5.3 CUSTOMER SATISFACTION

	DESCRIPTION OF PROGRAM	STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Is there a measurement system in place to assess the customer's perception of complete performance?			X	100	90
2.	Is an independent (unbiased) customer survey routinely conducted?			X	80	80
3.	Is there an internal measurement system within the organization which correlates to the level of customer satisfaction?			X	100	100
4.	Are there specific goals for achieving Total Customer Satisfaction, both internal and external?			X	100	90
5.	To what extent are customer satisfaction goals disseminated and understood by everyone in the organization?			X	100	90
6.	Does management regularly review and assess all operating systems to determine if barriers to customer satisfaction exist and are appropriate action plans then implemented?			X	100	90
7.	Is there a method in place to obtain future customer requirements?			X	80	70
8.	Are all findings of customer dissatisfaction reported back to the proper organization for analysis and corrective action?			X	100	90
9.	Are customer satisfaction requirements formally defined and documented, and are they based on customer input?			X	90	90
10.	Do all support organizations understand their role in achieving total customer satisfaction?			X	100	90

5.4 COMPUTER INTEGRATED MANUFACTURING

	DESCRIPTION OF PROGRAM	STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are systems integrated to allow electronic transfer of information between multiple systems to eliminate redundant data entry?			X	100	100
2.	Can customers electronically transfer CAD/CAM directly into manufacturing?			X	100	100
3.	Can customers electronically transfer order information directly into the business system?			X	100	100
4.	Is data electronically shared between shop floor control and process control systems (i.e., CNC, SPC, Electrical Test, AOI, etc.)?			X	100	100
5.	Are planning systems (MRP, forecasting, capacity planning, financial planning, etc.) electronically integrated with operation systems (order processing, purchasing, inventory management, shop floor control, financial/cost control, etc.)?			X	100	100
6.	Is information available from system processes in real time (vs. batch processing)?			X	100	90
7.	Are processes and procedures documented and available on-line?			X	80	80
8.	Do all functional departments have system access to key financial, manufacturing, sales, and operational data, as it relates to their functional objectives?			X	100	80
9.	Are computer simulation and design tools used to the maximum extent practicable in the design of new products/technologies/services			X	100	90

COMMENTS

We have "Procim" in place for integrated manufacturing data control.

5.5 PROCESS DOCUMENTATION		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are manufacturing product, process, and configuration documents under issue control?			X	100	100
2.	Are “preliminary” and “special product” specifications controlled?			X	100	100
3.	Does the system ensure that the most current customer specifications are available to the manufacturing personnel?			X	100	100
4.	Does the system ensure that the most current material specifications are available to the procurement function?			X	100	100
5.	Are incoming orders reviewed for revisions and issue changes?			X	100	100
6.	Is conformance to customer specifications assured before an order is accepted?			X	100	100
7.	Is customer feedback provided when designs do not meet manufacturability requirements?			X	100	100
8.	Are critical characteristics classified, relative to impact on product performance?			X	100	100
9.	Are customers informed of changes made to products controlled by customer drawings or specifications?			X	100	100
10.	Is there an effective internal deviation control procedure and, are customer requested deviations documented and followed?			X	100	100
11.	Do new product development procedures exist, and are they followed in the design development process?			X	100	80

5.6 QUALITY RECORDS		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are records of inspection and process control maintained and available for review?			X	100	100
2.	Are records of equipment and equipment maintenance kept?			X	100	100
3.	Is the record and sample retention program defined?			X	100	100
4.	Are quality data used as a basis for corrective action?			X	100	100
5.	Are quality data used in reporting performance and trends to management?			X	100	100
6.	Are quality data used in supporting certifications of quality furnished to customers?			X	100	100
7.	Is field information used for corrective action?			X	100	100
8.	Does a cost of quality measurement system exist?			X	80	80
9.	Are customer reported quality problems responded to, and resolved in the time period requested?			X	100	95
10.	Is quality information on production material rejects provided to sub-suppliers with required corrective action?			X	100	80
11.	Are computers used to collect and analyze quality data?			X	100	100

COMMENTS

Section 5.6

#8: Cost of quality measurement system exists, but usage as a tool at present is sporadic.

#10: It is done based on actual sub supplier involvement in corrective action investigations/root causes.

5.7 SKILLS, TRAINING, & CERTIFICATION		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Does management ensure that all personnel are trained in their role for achieving Total Customer Satisfaction?			X	100	100
2.	Do all personnel understand how their performance impacts internal and external customer satisfaction?			X	100	90
3.	Do all personnel who contact external customers reflect quality improvement programs?			X	100	100
4.	Do personnel participate in professional societies and growth programs?		X			
5.	Are all personnel trained in sufficient detail to support key initiatives?			X	100	100
6.	Are the results of training evaluated and indicated program changes made?			X	100	90
7.	Does a policy exist which encourages the cross training and rotation of personnel, and is this policy used as the basis of job progression?			X	100	90
8.	Are performance standards participatively developed, and regularly applied for all personnel?			X	100	100
9.	Are Total Customer Satisfaction programs and resulting successes publicized to all personnel?			X	100	100
10.	Do goal setting and reward/incentive programs support the quality improvement process?			X	50	50

5.8 SUBCONTRACTOR CONTROL		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are requirements defined, communicated, and updated to ensure that the supplier understands expectations?			X	100	100
2.	Does a system exist which measures the performance of the supplier and communicates such information to the supplier? (i.e., supplier rating system)			X	100	100
3.	Have the organization's processes been characterized to identify the critical requirements for the suppliers products?			X	100	100
4.	Have the capabilities of the supplier's processes been assessed and considered in the establishment of the requirements?			X	100	100
5.	Have partnerships been established with suppliers, and is assistance provided to ensure that each supplier has the capability to consistently supply conforming products?			X	100	100
6.	Have quality and cycle time metrics and improvement goals been established participatively with the supplier?			X	100	70
7.	Has a system been established with the supplier for identification and verification of corrective action?			X	100	100
8.	Have the requirements for supplier materials been properly characterized and specified to ensure conformance of the product/service to the customer satisfaction requirements?			X	100	100
9.	Is there a supplier certification program or equivalent procured material/service continuous quality improvement program?			X	100	100
10.	Can all personnel who contract suppliers properly reflect appropriate quality improvement programs and status to them?			X	100	100

COMMENTS

Section 5.7
#4: Company QMS does not dictate any employee professional affiliation requirements.
#10: Awards/Incentives are not mandatory based on QMS, but are given randomly per management consensus.

Section 5.8
#4: Assessment is done based on information provided by suppliers in their certificate of compliance reports.
#6: Metrics and goals have been established only with selective suppliers as applicable.

5.9 CALIBRATION CONTROL		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are calibration and preventative maintenance programs in place and documented?			X	100	100
2.	Are calibration and maintenance personnel trained?			X	100	100
3.	Is traceability to NIST maintained?	X				
4.	Is quality measurement and control equipment current, effective, and sufficiently integrated with production equipment?			X	100	100
5.	Is the history of quality measurement and control equipment documented?			X	100	100
6.	Has repeatability of measuring devices and inspection or testing processes been established and monitored; are gauge capability studies conducted and GR&R ratios acceptable(<10%)?			X	40	40
7.	Are calibration and preventative maintenance cycles on schedule?			X	100	100
8.	Is the use of non-calibrated equipment for design and production purposes prohibited?			X	100	100
9.	Are tools and fixtures used as criteria or acceptability of product/work fully qualified and identified?			X	100	100
10.	Are calibration intervals defined in accordance with industry standards or manufacturer's recommendations and the calibration history of the equipment?			X	100	100

5.10 INTERNAL AUDITS		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are regular reviews of the product/process conducted and are goals/plans established to continually improve?			X	100	100
2.	Are the processes/products properly documented and controlled? Do they include appropriate customer requirements and are they executed in conformance to the documentation?			X	100	100
3.	Are the required quality checks built into the operations within the manufacturing, field installation, and service process, and is the resulting data maintained and promptly acted upon?			X	100	100
4.	Are all pertinent methods of statistical quality control properly, effectively and efficiently used?			X	100	100
5.	Does a process change control system exist, and are customers informed of changes made to products and processes with customer approval prior to the change, when required?			X	100	100
6.	Are the operators within the process provided with written work instructions and are they trained?			X	100	100
7.	Is the receipt, handling, storage, packaging and release of all material, including customer provided items, at all stages, specified and controlled to prevent damage or deterioration, and to address obsolete material?			X	100	100
8.	Is there a first in/first out (FIFO) system in place, and is it followed?			X	100	100

COMMENTS

Section 5.9 #6:
40% of gages in system require R&R studies to be performed as per defined plan.

5.11 STATISTICAL PROCESS CONTROL		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Have the personnel who will be responsible for guiding the implementation of SPC been designated?			X	100	90
2.	Are statistical techniques used to reduce variation in the engineering process before the start of production?			X	100	100
3.	Is the quality system dependent upon process rather than product controls?			X	100	100
4.	Is the capability of critical processes and machines measured and monitored with CPK's >1.5, and targeted with CP of 2.0?			X	100	90
5.	Are incapable processes or machines targeted for improvement or replacement?			X	100	100
6.	Is SPC implemented for all critical processes?			X	100	100
7.	Are procedures that control the reaction to out-of-control situations adequate and effective?			X	100	100
8.	Are operators trained in the use of appropriate statistical techniques, and are they properly applying them?			X	90	80
9.	Are advanced problem solving techniques used by engineers to solve problems? (Design of Experiments, planned experimentation, advanced diagnostic tools, etc.)			X	70	60
10.	Are control charts and other process controls properly implemented?			X	90	90
11.	Is statistical process control being practiced in work centers and are yields being recorded and plotted on a scheduled basis, with respect to upper and lower control limits?			X	100	90

5.12 PROBLEM SOLVING		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are employees trained in problem solving techniques, in comparison to the needs of the organization?			X	100	90
2.	Does the organization utilize participative problem solving techniques to identify, measure and resolve internal and external problems?			X	100	90
3.	Are problem solving efforts timely and effective?			X	100	90
4.	Are applied resources sufficient to remove problem solving constraints?			X	100	90
5.	Are statistical techniques used for problem solving?			X	90	80
6.	Are quality data used to identify barriers, and to determine the priority of problems?			X	100	100
7.	Is there a policy/procedure that includes the use of problem solving techniques to systematically drive reduction in variability?		X			

COMMENTS

Section 5.12 #7:
QMS does not document requirement for subject techniques to be utilized to reduce variability.
Subject techniques are often used, but not as a procedural or mandatory requirements under QMS plan.

5.13 IN-PROCESS CONTROL		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are process capabilities established and maintained on all major processes? (critical parameters)			X	100	100
2.	Are in-process inspections, test operations, and processes properly specified and performed?			X	100	100
3.	Are in-process inspection facilities and equipment adequate?			X	100	100
4.	Are the results of in-process inspections used in the promotion of effective preventative action and corrective action?			X	100	100
5.	Is preventative maintenance performed on the equipment and facilities?			X	100	100
6.	Are housekeeping procedures adequate and how well are they followed?			X	100	80
7.	Are process management plans established, and are critical parameters followed?			X	100	100
8.	Are work areas uncluttered and free of excess work-in-process, supplies, debris, etc? Is the environment conductive to producing quality work? Is proprietary information adequately protected?			X	100	85
9.	Are certifications and in-process inspection results used in making final acceptance decisions?			X	100	100
10.	Are methods and procedures for the control of metallurgical, chemical, and other special processes established and followed?			X	100	100

5.14 RECEIVING INSPECTION		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are receiving inspection facilities and equipment adequately and properly maintained?			X	100	100
2.	Are receiving inspection procedures documented and followed?			X	100	100
3.	Are receiving inspection results used for corrective and preventive action?			X	100	100
4.	Are the procedures for storage and timely disposition of discrepant material in place and followed?			X	100	100

COMMENTS

5.14 Receiving Inspection:

We use standard brands and pre-qualified materials. We perform sampling checks only at receiving inspection. We insist on certificate of conformance (compliance) from our suppliers.

5.15 MATERIAL HANDLING		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are procured material releases from receiving inspection clearly identified, as to acceptance status?			X	100	100
2.	Are procedures to facilitate limited life materials, such as prepreg, in place, properly controlled, and monitored?			X	100	100
3.	Are procured items identified with some means of traceability (serial number, lot number, date code, etc.)?			X	100	100
4.	Are procedures and facilities adequate for storage, release and control of materials?			X	100	100
5.	Are in-store and in-process materials properly identified and controlled?			X	100	100
6.	Is in-process material protected from corrosion, deterioration, and damage?			X	100	100

5.16 NON-CONFORMING MATERIAL CONTROL		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Is non-conforming material identified, segregated from regular production material, and properly dispositioned?			X	100	100
2.	Are non-conforming materials properly identified and controlled to prevent inadvertent use?			X	100	100
3.	Is the review and disposition of non-conforming materials defined, and are provisions made for inclusion of the customer in disposition decision?			X	100	100
4.	Are procedures for controlling non-conforming materials, and for ensuing corrective action, in place and followed?			X	100	100
5.	Do procedures provide for material review by a committee consisting of Quality and Engineering (as a minimum), to determine the disposition of non-conforming materials? (deviating from drawings or specification)			X	100	100
6.	Do supplier's procedures and controls for corrective action prevent recurrence of non-conformances?			X	100	100
7.	Is there a system for coordinating necessary corrective action with purchasing personnel?			X	100	100
8.	Does the corrective action extend to all applicable causes of non-conformance (e.g., design, workmanship, procedures, equipment, etc.)?			X	100	100

COMMENTS

5.17 INSPECTION AND TEST PLAN		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are statistical techniques used in determining the acceptability of finished goods to customer requirements?			X	100	100
2.	Are periodic tests conducted to audit reliability and environmental performance of the final product?			X	100	100
3.	Is CPK tracking performed for critical characteristics, with plans to achieve CPK = 1.5 with a target of CP of 2.0?			X	100	100
4.	Is root cause failure analysis performed for internal and external failures, and is appropriate corrective action implemented?			X	100	100
5.	Are test and inspection personnel trained in the procedures of their operations, and are those procedures being followed?			X	100	100
6.	Is the new product/technology/service, as produced by the processes, verified to meet all customer satisfaction requirements?			X	100	100

5.18 PRODUCT INSPECTION/FINAL AUDIT		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are final product acceptance procedures documented and followed?			X	100	100
2.	Are all specific customer product audits conducted, as required?			X	100	100
3.	Are inspectors trained for the tasks performed?			X	100	100
4.	Are flow charts or milestones developed with checkpoints readily available?			X	100	100
5.	Is a system in place which denotes inspection performed; e.g., use of initials, stamps, labels, bar codes, etc., affixed to production documentation?			X	100	100
6.	Is a quality system established and maintained for control of product/production documentation?			X	100	100
7.	Is “accept/reject” criteria defined and available for use?			X	100	100
8.	Is a final audit performed to ensure that all required verifications and tests, from receipt of materials through point of product completion, have been accomplished?			X	100	100
9.	Are packing and order checking procedures documented and followed?			X	100	100

COMMENTS

5.19 TOOLING INSPECTION, HANDLING, & STORAGE		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are temperature, humidity, laminar flow controls in place to prevent contamination, and to assure dimensional stability?			X	100	100
2.	Do operators use hairnets, gloves & lab coats in all photo lab and photo exposure areas?			X	100	100
3.	Are work instructions and related forms in place to control all applicable tooling requirements, as stated in the customer's purchase order?			X	100	100
4.	Are customer provided artworks controlled with regard to handling, storage, revision control and relationship to converted production photo tools (working films)?			X	100	100
5.	Are production photo tools (working films) controlled with regard to handling, storage, use life, and relationship to customer purchase order?			X	100	100
6.	Are customer provided artworks and production photo tools (working films) inspected, including dimensional checks?			X	100	100
7.	Are all tools, fixtures, and other devices, used for tooling inspection and control, maintained under the calibration control procedure?			X	100	100
8.	Are records showing initial acceptance, periodic checks, and any needs for rework and/or modification available?			X	100	100

5.20 CORRECTIVE ACTION		STATUS				
	DESCRIPTION OF PROGRAM	Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are final acceptance inspection results used for corrective and preventative action?			X	100	100
2.	Is root-cause analysis performed for non-conformances? This includes, but is not limited to, non-conformances (problems) caused by suppliers, found/caused "in-house" during processing, or those reported by the customer.			X	100	100
3.	Is positive action taken to prevent recurrence of problems, and are there documented reports/records of each occasion?			X	100	100
4.	Do procedures and systems provide for ensuring that replies are made to customer requests for correction action within the time limit specified?			X	100	100
5.	Is corrective action controlled and documented for all applicable work centers?			X	100	100
6.	When corrections are made, is their effectiveness subsequently reviewed and monitored?			X	100	100

COMMENTS

DATE COMPLETED

Available on request

SECTION 6 (CHECK ONE IN EACH LINE THAT APPLIES)

MANUFACTURING HISTORY

(See Section 2 Site Capability)

Please complete as many history profiles so that the total descriptions of products you manufacture account for production orders that reflect 70% of your business. History profiles are for board or board family (board types may be grounded together if they are similar).

BOARD TYPE	DATE OF ORDER	MATERIAL	HISTORY #
VIA TYPE	PRODUCTION QUANTITY	TOTAL YEARLY PRODUCTION %	

Dimensions in millimeters (inches in brackets)

BOARD			HOLES		
BOARD SIZE DIAGONAL	TOTAL BOARD THICKNESS	NUMBER CONDUCTIVE LAYERS	DIA DRILLED HOLES	TOTAL PTH TOL (MAX-MIN)	LOCATION TOL DTP
☐<250 [<10.00]	☐<1,0 [<.040]	☐1-4 [1-4]	☐>0,5 [>.020]	☐>0,250 [> .010]	☐>0,50 [>.020]
☐250 [10.00]	☐1,0 [.040]	☐5-6 [5-6]	☐0,5 [.020]	☐0,250 [.010]	☐0,50 [.020]
☐350 [14.00]	☐1,6 [.060]	☐7-8 [7-8]	☐0,4 [.016]	☐0,200 [.008]	☐0,40 [.016]
☐450[17.50]	☐2,0 [.080]	☐9-12 [9-12]	☐0,35 [.014]	☐0,150 [.006]	☐0,30 [.012]
☐550 [21.50]	☐2,5 [.100]	☐13-16 [13-16]	☐0,30 [.012]	☐0,125 [.005]	☐0,25 [.010]
☐650 [25.50]	☐3,5 [.135]	☐17-20 [17-20]	☐0,25 [.010]	☐0,100 [.004]	☐0,20 [.008]
☐750 [29.50]	☐5,0 [.200]	☐21-24 [21-24]	☐0,20 [.008]	☐0,075 [.003]	☐0,15 [.006]
☐850 [33.50]	☐6,5 [.250]	☐25-28 [25-28]	☐0,15 [.006]	☐0,050 [.002]	☐0,10 [.004]
☐>850 [>33.50]	☐>6,5 [>.250]	☐>28 [>28]	☐<0,15 [.006]	☐<0,050 [<.002]	☐<0,10 [<.004]
☐Other:	☐Other:	☐Other:	☐Other:	☐Other:	☐Other:

CONDUCTORS						
INTERNAL ELEC CLEARANCE (MIN)	INTERNAL COND WIDTH (MIN)	INTERNAL PROCESS ALLOWANCE	EXTERNAL ELEC CLEARANCE (MIN)	EXTERNAL COND WIDTH (MIN)	EXTERNAL PROCESS ALLOWANCE	FEATURE LOCATION DTP
☐>0,350 [>.014]	☐>0,250 [>.010]	☐>0,100 [>.004]	☐>0,350 [>.014]	☐>0,250 [>.010]	☐>0,100 [>.004]	☐>0,50 [>.020]
☐0,350 [.014]	☐0,250 [.010]	☐0,100 [.004]	☐0,350 [.014]	☐0,250 [.010]	☐0,100 [.004]	☐0,50 [.020]
☐0,250 [.010]	☐0,200 [.008]	☐0,075 [.003]	☐0,250 [.010]	☐0,200 [.008]	☐0,075 [.003]	☐0,40 [.016]
☐0,200 [.008]	☐0,150 [.006]	☐0,050 [.002]	☐0,200 [.008]	☐0,150 [.006]	☐0,050 [.002]	☐0,30 [.012]
☐0,150 [.005]	☐0,125 [.005]	☐0,040 [.0015]	☐0,150 [.006]	☐0,125 [.005]	☐0,040 [.0015]	☐0,25 [.010]
☐0,125 [.005]	☐0,100 [.004]	☐0,030 [.0012]	☐0,125 [.005]	☐0,100 [.004]	☐0,030 [.0012]	☐0,20 [.008]
☐0,100 [.004]	☐0,075 [.003]	☐0,025 [.001]	☐0,100 [.004]	☐0,075 [.003]	☐0,025 [.001]	☐0,15 [.006]
☐0,075 [.003]	☐0,050 [.002]	☐0,020 [.0008]	☐0,075 [.003]	☐0,050 [.002]	☐0,020 [.0008]	☐0,10 [.004]
☐<0,075 [<.003]	☐<0,050 [<.002]	☐<0,020 [<.0008]	☐<0,075 [<.003]	☐<0,050 [<.002]	☐<0,020 [<.008]	☐<0,10 [<.004]
☐Other:	☐Other:	☐Other:	☐Other:	☐Other:	☐Other:	☐Other:

DATE COMPLETED
01 / March / 2014
(Rest Available on Request)

SECTION 7

IDENTIFICATION OF PREVIOUS AUDITS (Optional)

Please complete as many forms as you feel reflect the intensity of your customer visits.

COMPANY AUDITORS ISO Certification Audit Details: Our Certification Body for ISO 9001 2008 is: NSF-ISR (Previously known as AQA = American Quality Assessors)	DATE OF AUDIT 29th & 30th January 2014 Re-registration Audit (Start Registration Date: 2 NOVEMBER 2004)
AUDIT TEAM MEMBERS Mr. N. Vardraj Prabhu - Audit Team Leader Mr. D.P. Shaha - Audit Team Member	AUDITOR REMARKS To NSF-ISR (AQA): Recommendation to maintain registration
	SPECIFICATIONS USED IN AUDIT ISO 9001 2008
LENGHT OF AUDIT Four Man Days	
TEAM MEMBERS MAY BE CONTACTED AT AQA International India, Office at Hyderabad. Telephone Nos: +91-40-23301618 / 23301554 / 23301582	

COMPANY AUDITORS	DATE OF AUDIT
AUDIT TEAM MEMBERS	AUDITOR REMARKS
	SPECIFICATIONS USED IN AUDIT
LENGHT OF AUDIT	
TEAM MEMBERS MAY BE CONTACTED AT	

COMPANY AUDITORS	DATE OF AUDIT
AUDIT TEAM MEMBERS	AUDITOR REMARKS
	SPECIFICATIONS USED IN AUDIT
LENGHT OF AUDIT	
TEAM MEMBERS MAY BE CONTACT AT	

*REPEAT THIS FORM AS NECESSARY

SECTION 8

DATE COMPLETED
Available on Request

FINANCIAL REVIEW (OPTIONAL)

Please complete the following financial information that coincides with the company description and site information provided in section 1.

COMPANY FINANCIAL DESCRIPTION		
LEGAL NAME		
TAXPAYER ID NUMBER	DUNS NUMBER	TRADING SYMBOL
ANNUAL SALES	PRIOR YEAR	YEAR-TO-DATE
FISCAL YEAR		
BANK	ACCOUNT NUMBER	
BANK ADDRESS	STATE	ZIP
PROVINCE	COUNTRY	
BANK TELEPHONE NUMBER	FAX NUMBER	
COMMENTS		

SITE FINANCIAL DESCRIPTION		
SITE NAME		
TAXPAYER ID NUMBER	DUNS NUMBER	TRADING SYMBOL
ANNUAL SALES	PRIOR YEAR	YEAR-TO-DATE
FISCAL YEAR		
BANK	ACCOUNT NUMBER	
BANK ADDRESS	STATE	ZIP
PROVINCE	COUNTRY	
BANK TELEPHONE NUMBER	FAX NUMBER	
COMMENTS		

SECTION 9
MQP ELECTRONIC EDITING

This MS Word template comes with editable fields. IPC has made this electronic document available for ease of completing, updating, and filing the MQP, as well as to give the laminate manufacturer and customer a common interface. Using the template enables laminate manufacturers to maintain several customer specific files without the endless stream of paperwork.

Editable fields are highlighted in gray. To complete the fields in the template, use the TAB key to toggle from field to field, entering the information as instructed in the introductory text for each section.

The developers of this MQP strongly suggest the person at the laminate manufacturing facility responsible for creating and maintaining the MQP write protect the file to be sent.